3 Key Advances in TEC Design

Challenges in the market:

Today, content providers in the datacom space are releasing new technology faster than ever, demanding the same pace of development from transceiver and optical components providers. You need to innovate fast, without increasing cost, to keep up with this demand.

There's a global effort to lower power consumption, reducing operating costs. But traditional TECs can be one of the larger power drains in the TOSA. As power consumption budgets tighten, you need to find ways to increase efficiency across every part of your package - and a great place to start is the TEC.

Five major trends influencing laser package designs:

- Increasing heat density as form factors shrink
- Increasing maximum ambient temperatures, from C-Temp to I-Temp
- Increasing power consumption budget stringency, as defined in MSA specifications
- Optics moving closer to CPUs, forcing a switch from electrons to light. Innovation in on-board optics will require new cooling approaches
- Environmental challenges introduced by non-hermetic packages that reduce package complexity and cost

How do we deliver all this? We're obsessed with performance.
A TEC isn’t just a TEC. A Phononic TEC is different.

Contact us today - we’ll assess your system requirements and partner with you on TEC design and development for your cooled TOSA.